Inventor:

Paul A. Morgan

Title:

Methods of Cleaning Surfaces of Copper-Containing Materials, and Methods

of Forming Openings to Copper-Containings Substrates

Assignee:

Micron Technology, Inc.

INFORMATION DISCLOSURE STATEMENT

PURSUANT TO 37 C.F.R. §§ 1.56, 1.97 AND 1.98

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is

directed to the United States patents and other references listed on the attached

Form PTO-1449. No admission is made regarding whether all the submitted

references are prior art.

The listed references were cited by, or submitted to, the Office in the

parent, co-pending application of the above-identified application. The above-

identified application is a continuation application of co-pending application Serial

No. 09/579,333, filed May 25, 2000. Such prior disclosure is sufficient for the

above-identified application as far as copies of the references are concerned.

37 C.F.R. § 1.98(d) and MPEP § 609(2).

Citation of these references is respectfully requested.

Respectfully submitted,

Dated: Octobry 10, 2003 By:

Form PTO-144	19	U.S. DEPARTMEN PATENT AND TRA				IT OF COMMERCE DEMARK OFFICE	ATTY, DOCKET NO. MI22-2411			SERIAL NO. 09/579,333		
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)					NT		APPLICANT Paul A. Morgan					
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		- · · · ·		ENT DOCUMENTS								
*Examiner Initial		Document Number		Date		Name		Class	Subclass		Filing Date If Appropriate	
	AA	6,232,228 B1		05-2001	Kwag et al	al.						
	AB	6,143,658		11-2000	Donnelly, J	nelly, Jr. et al.						
	AC	5,017,267		05-1991	Cordani	Cordani						
	AD	5,213,622		05-1993	Bohling et	Bohling et al.						
	AE	5,382,296		01-1995	Anttila	Anttila						
	AF	5,863,344		01-1999	Nam	Nam						
	AG	6,136,767		10-2000	Hineman e	neman et al.						
	АН	5,633,121		05-1997	Namiki et	iki et al.						
	Al	4,938,257		07-1990	Morris	Morris						-
	AJ	6,083,840		07-2000	Mravic et	Mravic et al.						
	AK	5,681,398		10-1997	Muraoka	Muraoka						
	AL	3,831,265		08-1974	Louzon et	Louzon et al.						
					FOREIGN PA	ATENT DOCUMENT	rs					
		Document Number		Date		Country			Sub	class		lation
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U.S. PATENT DOCUMENTS										
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate			
	AA	6,361,712	03/02	Honda et al.	Honda et al.					
	AB	6,391,794								
	AC	6,319,543	11-01	Soutar et al.	ioutar et al.					
	AD	5,861,076	01/99	Adlam et al.	Adlam et al.					
	AE	6,541,391 B2	04-2003	Smith et al.	h et al.					
	AF	6,589,882 B2	07-2003	Andreas et al.						
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